



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2022-11-10
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G071CBT7 STM32G071CBT7TR	765B*460XXB	A	998Z	2022-11-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	178.57	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7	48	L bend	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	765B*460XXB				999998.0	999997.4				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	5.168	mg	Supplier	die	Silicon (Si)	7440-21-3		4.971	mg	961881	27838				
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	1741	50				
				Supplier	metallization	Copper (Cu)	7440-50-8		0.084	mg	16254	470				
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.027	mg	5224	151				
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	193	6				
				Supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	193	6				
				Supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	4063	118				
				Supplier	Passivation	Silicon Oxide	7631-86-9		0.054	mg	10449	302				
				DA_Ablestik_3230_Henkel	M-011 Other inorganic materials	0.692	mg	Supplier	Metals	Silver	7440-22-4		0.564	mg	815000	3159
								Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))	39817-09-9		0.021	mg	30000	116
Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7						0.021	mg	30000	116				
Supplier	Organic Compounds	Epoxy resin	Proprietary						0.021	mg	30000	116				
Supplier	Organic Compounds	Dodecylloxirane	3234-28-4						0.021	mg	30000	116				
Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0						0.021	mg	30000	116				
Supplier	Organic Compounds	Epoxy resin modifier	Proprietary						0.021	mg	30000	116				
Supplier	Metallic compounds	Copper oxide	1317-38-0						0.003	mg	5000	19				
Encapsulation_EME-G631SHQ_Sumit	M-011 Other inorganic materials	119.854	mg					Supplier	Plastics/polymers	Epoxy Resin A	Trade Secret		2.517	mg	21000	14095
								Supplier	Plastics/polymers	Epoxy Resin B	Trade Secret		2.517	mg	21000	14095
				Supplier	Plastics/polymers	Phenol Resin	Trade Secret		6.712	mg	56000	37587				
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		93.540	mg	780450	523838				
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		13.822	mg	115320	77403				
				Supplier	Non-metals	Carbon Black	1333-86-4		0.747	mg	6230	4182				
Wire_AUHA3_HERAUS	Bonding Wire	0.767	mg	Supplier	Metals	Gold	7440-57-5		0.767	mg	1000000	4294				
Plating anode_Pure Tin_ASAMI	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	6039				
Leadframe_C194+Ag_MITSUI	Copper & its alloys	51.007	mg	Supplier	Metals	Copper	7440-50-8		49.589	mg	972200	277706				
				Supplier	Metals	Iron	7439-89-6		1.168	mg	22900	6541				
				Supplier	Metals	Zinc	7440-66-6		0.077	mg	1500	428				
				Supplier	Metals	Phosphorus	7723-14-0		0.015	mg	300	86				
				Supplier	Metals	Silver	7440-22-4		0.158	mg	3100	886				